



# InspireSemi™

Disruptive Next Generation Accelerated  
Computing Platform

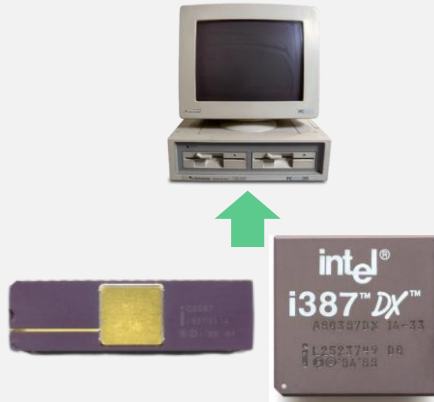
Blistering speed, energy efficiency,  
versatility, and affordability for HPC/AI  
and graph analytics applications

**RISC-V Workshop at SC24**  
November 2024

# The Third Wave of Accelerated Computing is Here

## *Thunderbird for HPC, AI, Graph Analytics*

### 1980 Math Coprocessor



- Purpose-built widely applicable
- Open software ecosystem
- Plugs into existing computers

### 2007 GPU, FPGA



- Limited applications benefit
- Proprietary software model
- Plugs into existing servers



### 2024+ Thunderbird

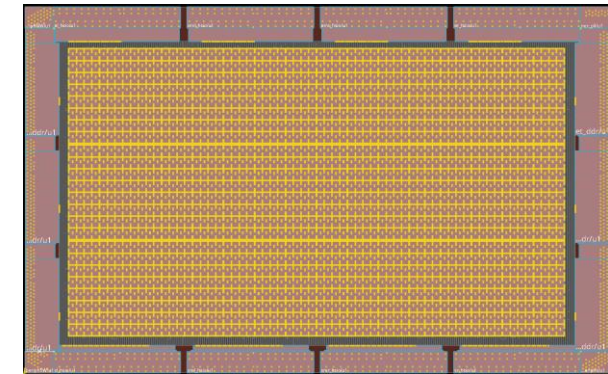


- Built for HPC
- Versatile & open software ecosystem
- Plugs into existing servers



# Thunderbird Accelerated Computing Solution

- **Ultra-Efficient, Ultra-compact custom CPU cores**
  - Based on RISC-V instruction set (like ARM but open standard)
  - Modern superscalar, out-of-order, vector-capable cores
  - Ability to add custom instructions
- **A supercomputer cluster-on-a-chip**
  - 1,536 high-perf 64-bit CPU cores per chip (>6,000 per PCIe card)
  - Comparable to GPU shader count but are independent CPUs
- **Innovative low latency interconnect fabric**
  - Key to efficient utilization of so many cores
  - Seamlessly spans multiple-chip arrays up to 256 chips!
- **Best in class energy efficiency**
  - Focus on performance/watt: 75 GLOPS/Watt (FP64)
  - Higher energy efficiency, fits in current datacenters
- **Supporting existing open RISC-V software ecosystem**
  - Enables customers to easily adapt their software programs
  - Fast – no big investment or training required
- **Recognized global partners to deliver turnkey solutions**
  - High-volume across multiple markets and geographies





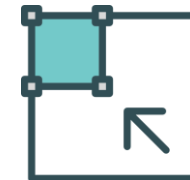
# Thunderbird Datacenter Impact:

## *Significant datacenter TCO savings and carbon footprint reduction*

- Thunderbird has >20X CPU cores vs. Intel/AMD CPU cores per board
  - Intel and AMD CPUs: Latest have 256 bloated cores per board
  - Thunderbird I: 6,144 custom, low-power, low-area cores per board
- One Thunderbird card has more CPU cores than an ***entire rack of standard Intel/AMD servers!***
  - Less complexity, servers, power, HVAC, interconnects, points of failure, real estate

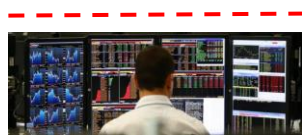


4U Server with 8 Thunderbird cards

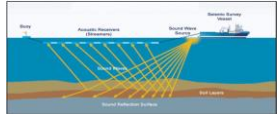


# Addressing the Need to Accelerate All HPC & AI Software

*What customers always wanted...not “yet another GPU”*



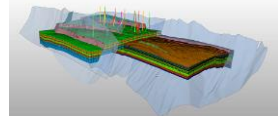
Financial  
simulations



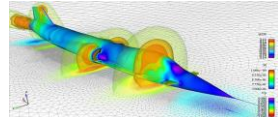
Geology: Seismic



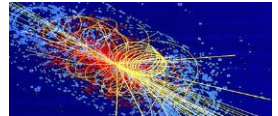
Financial Trading &  
Graph Analytics



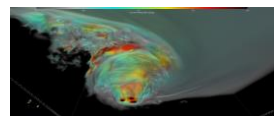
Energy: Reservoir  
Modeling & Sim



CAE/Computational  
Fluid Dynamics



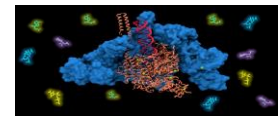
Government Lab  
Simulations



Climate & Weather  
Modeling



Cybersecurity &  
Cryptography



Genomics, Pharma,  
Life Sciences

Datacenter  
GPUs



Datacenter  
GPUs do it  
all, right?  
InspireSemi  
Thunderbird



Highly differentiated “supercomputer-cluster-on-a-chip”

- Versatile platform delivers unprecedented capability
- 4 chip PCIe card delivers >6,000 64-bit CPU cores (FP64)
- Innovative high bandwidth, low-latency on-chip network
- Best-in-class for both Performance/\$ and Watt
- Large scale computing power with much lower TCO - can replace many racks of servers and expensive high-speed networking

# Open Software Ecosystem Solves Customer Porting Challenges

- Supports standard operating systems (unlike competing compute accelerators)
  - **Linux!**
  - Real-Time Operating Systems (RTOS)
  - Kitten lightweight kernel (LWK for DOE labs)
  - Eliminates need to learn and use proprietary software stacks
  - Eliminates vendor lock-in
- Uses standard CPU-style programming models
  - No need for CUDA, ROCM, etc. that GPUs require
  - No need for disruptive software algorithm rewrites
  - Standard compiler, OpenMP, MPI, etc. approaches
- Leverages key RISC-V software ecosystem
  - Address-accurate QEMU model
  - Standard compilers, e.g.- GCC, Gfortran, GDB toolchains
  - Standard HPC libraries, e.g. – BLAS, LAPACK, FFTW



# Thunderbird Performance Specifications

**6 – 8 TFLOPS**  
*per chip (FP64)*  
**24 – 32 TFLOPS**  
*per card (FP64)*

**75 GFLOPS/  
Watt**  
*(FP64)*

**20x**  
*reduction in latency*

**30 – 60%**  
*lower power consumptions*

Early customer feedback is unlike GPUs, Thunderbird is likely to hit its peak performance numbers due to its architecture and interconnect technology



# InspireSemi Thunderbird in the News

**techradar.**

Supercomputer-on-a-chip goes live: single PCIe card packs more than 6,000 RISC-V cores, with the ability to scale to more than 360,000 cores

- InspireSemi has announced the successful tapeout of the Thunderbird I Accelerated Computing chip for fabrication at TSMC

**tom's****HARDWARE**

Thunderbird packs up to 6,144 CPU cores into a single AI accelerator and scales up to 360,000 cores — InspireSemi's RISC-V 'supercomputer-cluster-on-a-chip' touts higher performance than Nvidia GPUs

- The Holy Grail of supercomputing chip design is an architecture that combines the versatility and programmability of CPUs with the explicit parallelism of GPUs, and InspireSemi strives to achieve just that

**TECHSPOT**

Move over GPUs, with 1,536 cores the Thunderbird RISC-V CPU is ready to eat your lunch

- Open source enables small industries to participate in the accelerator boom

**ALL ABOUT  
CIRCUITS**

InspireSemi Announces Tapeout of Thunderbird Accelerated Computing Chip

- InspireSemi's new compute chip couples the parallel processing of GPUs with the versatility of CPUs

**JPR**  
Jon Peddie Research

InspireSemi announces tape-out of RISC-V HPC chip

- InspireSemi's Thunderbird I RISC-V chip offers high-performance computing for underserved applications, with an emphasis on energy efficiency and competitive pricing



# Thunderbird Addresses ALL HPC & AI Customer Needs

	InspireSemi Thunderbird	CPU	GPU	FPGA	AI Accelerators
Architecture	Many programs, many data streams	Few programs, few data streams	Few programs, many data streams	Programmable logic elements	Single program, many data streams
Performance	High for broad range of HPC apps	Slow, need h/w accelerators	High for AI and some HPC apps	Medium	High for AI only
Cost	Low \$6,500 for 2 chip PCIe card	High ~\$1K-8K (+ more servers)	High ~\$7K-48K	High \$8K-\$10K	High ~\$10K - \$2.2M
Energy consumption	Low ~50W/chip (150W max)	Med 290W+/chip (+ more servers)	High 700-1,000W	High ~300W	High ~300W - 20kW
Scalability	256 chips	1-4 chips	2-8 chips	1 chip	1-2 chips
Programming model	Standard CPU-like, Any language, Full instruction set	Standard CPU, Any language, Full instruction set	Specialized C variant (CUDA, ROCM, SYCL)	Hardware description language	Proprietary, obscure
Software ecosystem	Open-source, Linux, compilers, libraries, AI frameworks, existing applications	Robust	Limited, proprietary	None	AI frameworks and proprietary software stacks

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